



TSM2311

20V P-Channel Enhancement Mode MOSFET

SOT-23



Pin assignment:

1. Gate
2. Source
3. Drain

$$V_{DS} = -20V$$

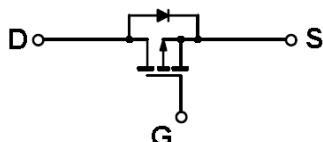
$$R_{DS(on)}, V_{GS} @ -4.5V, I_{DS} @ -4.0A = 55m\Omega$$

$$R_{DS(on)}, V_{GS} @ -2.5V, I_{DS} @ -2.5A = 85m\Omega$$

Features

- ◊ Advanced trench process technology
- ◊ High density cell design for ultra low on-resistance
- ◊ Excellent thermal and electrical capabilities
- ◊ Compact and low profile SOT-23 package

Block Diagram



Ordering Information

| Part No. | Packing | Package |
|-----------|-------------|---------|
| TSM2311CX | Tape & Reel | SOT-23 |

Absolute Maximum Rating ($T_a = 25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|--------------------|-------------|------------|
| Drain-Source Voltage | V_{DS} | -20V | V |
| Gate-Source Voltage | V_{GS} | ± 8 | V |
| Continuous Drain Current | I_D | -4 | A |
| Pulsed Drain Current | I_{DM} | -20 | A |
| Maximum Power Dissipation | $T_a = 25^\circ C$ | P_D | 1.25 |
| | $T_a = 75^\circ C$ | | 0.8 |
| Operating Junction Temperature | T_J | +150 | $^\circ C$ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ C$ |

Thermal Performance

| Parameter | Symbol | Limit | Unit |
|--|-----------------|-------|--------------|
| Lead Temperature (1/8" from case) | T_L | 5 | S |
| Junction to Ambient Thermal Resistance (PCB mounted) | $R_{\theta ja}$ | 100 | $^\circ C/W$ |

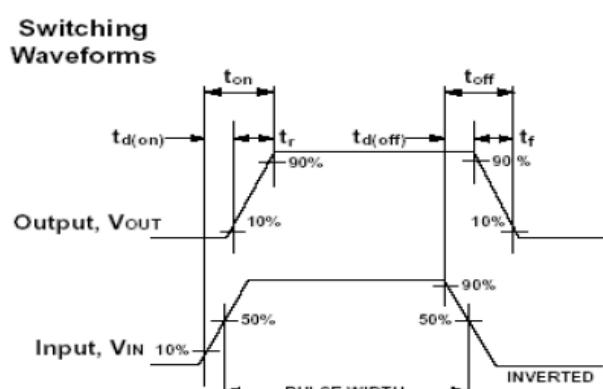
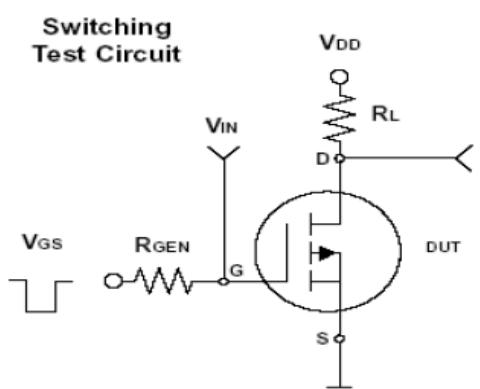
Note: Surface mounted on FR4 board $t \leq 5\text{sec}$.

Electrical Characteristics

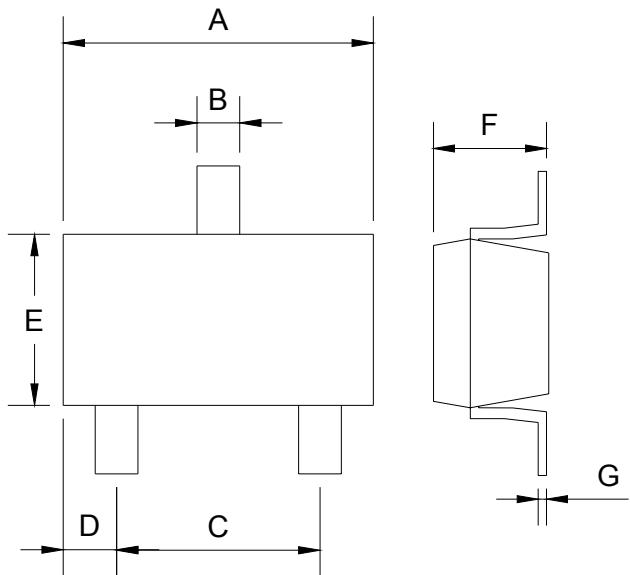
T_a = 25 °C, unless otherwise noted

| Parameter | Conditions | Symbol | Min | Typ | Max | Unit |
|----------------------------------|--|---------------------|--------|-------|-------|------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{GS} = 0V, I _D = - 250uA | BV _{DSS} | - 20 | -- | -- | V |
| Drain-Source On-State Resistance | V _{GS} = - 4.5V, I _D = -4.0A | R _{DS(ON)} | -- | 45 | 55 | mΩ |
| Drain-Source On-State Resistance | V _{GS} = - 2.5V, I _D = -2.5A | R _{DS(ON)} | -- | 75 | 85 | |
| Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = - 250uA | V _{GS(TH)} | - 0.45 | -- | -- | V |
| Zero Gate Voltage Drain Current | V _{DS} = - 16V, V _{GS} = 0V | I _{DSS} | -- | -- | - 1.0 | uA |
| Gate Body Leakage | V _{GS} = ± 8V, V _{DS} = 0V | I _{GSS} | -- | -- | ± 100 | nA |
| On-State Drain Current | V _{DS} ≥ - 10V, V _{GS} = -4.5V | I _{D(ON)} | - 6 | -- | -- | A |
| Forward Transconductance | V _{DS} = - 5V, I _D = - 4.0A | g _{fs} | -- | 9 | -- | S |
| Dynamic | | | | | | |
| Total Gate Charge | V _{DS} = - 6V, I _D = - 4.0A, V _{GS} = - 4.5V | Q _g | -- | 8.5 | 12 | nC |
| Gate-Source Charge | | Q _{gs} | -- | 1.5 | -- | |
| Gate-Drain Charge | | Q _{gd} | -- | 2.1 | -- | |
| Turn-On Delay Time | V _{DD} = - 4V, R _L = 4Ω, I _D = - 1A, V _{GEN} = - 4.5V, R _G = 6Ω | t _{d(on)} | -- | 18 | -- | nS |
| Turn-On Rise Time | | t _r | -- | 45 | -- | |
| Turn-Off Delay Time | | t _{d(off)} | -- | 95 | -- | |
| Turn-Off Fall Time | | t _f | -- | 65 | -- | |
| Input Capacitance | V _{DS} = - 6V, V _{GS} = 0V, f = 1.0MHz | C _{iss} | -- | 970 | -- | pF |
| Output Capacitance | | C _{oss} | -- | 485 | -- | |
| Reverse Transfer Capacitance | | C _{rss} | -- | 160 | -- | |
| Source-Drain Diode | | | | | | |
| Max. Diode Forward Current | | I _S | -- | -- | - 1.6 | A |
| Diode Forward Voltage | I _S = - 1.6A, V _{GS} = 0V | V _{SD} | -- | - 0.8 | - 1.2 | V |

Note : pulse test: pulse width <=300uS, duty cycle <=2%



SOT-23 Mechanical Drawing



| SOT-23 DIMENSION | | | | |
|------------------|-------------|------|--------|-------|
| DIM | MILLIMETERS | | INCHES | |
| | MIN | MAX | MIN | MAX |
| A | 2.88 | 2.91 | 0.113 | 0.115 |
| B | 0.39 | 0.42 | 0.015 | 0.017 |
| C | 1.78 | 2.03 | 0.070 | 0.080 |
| D | 0.51 | 0.61 | 0.020 | 0.024 |
| E | 1.59 | 1.66 | 0.063 | 0.065 |
| F | 1.04 | 1.08 | 0.041 | 0.043 |
| G | 0.07 | 0.09 | 0.003 | 0.004 |